





SLD-68-026

Eye Response Silicon Photodiode-Filter Combination

The SLD-68-026 is a 2.5mm² active area blue-enhanced Silicon photodiode combined with a high-quality color-correction filter resulting in a spectral response approximating a human eye. Packaged in a TO-46 package with epoxy dome lens allows a wide angle of detection. The photodiode is suitable for photopic sensing applications such as: color sensing, analytics, safety equipment and special sensors for automation. Low dark current and low capacitance make it the ideal detector for visible light detection applications.

Applications

Industrial Sensing

Features

Human Eye Response Low Capacitance Low Dark Current Linear Response vs. Irradiance

TO-46 Base with Epoxy Dome Lens





Absolute Maximum Ratings at T_A=23 °C

Parameter	Symbol	Min	Мах	Unit
Operating Temperature*	T _{OP}	-20	+75	°C
Storage Temperature	T _{stg}	-20	+75	°C

*Non condensing

Typical Electro-Optical Specifications at $T_A = 23 \text{ °C}$

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Sensitivity Spectral Range	V _R =0V	-	400	-	700	μΑ
Short Circuit Current	V_R =5V, Ee=25mW/cm ²	I _{sc}	7.5	11.0	-	μΑ
Open Circuit Current	Ee=25mw/cm ² (1)	C	-	-	-	V
Reverse Breakdown Voltage	I _R =100 μΑ	V _{bd}	-	50	-	V
Capacitance	V _R =0, Ee=0, f=1MHz	C」	-	40	-	pF
Reverse Dark Current	V _R =5V, Ee=0	I _D	-	-	100	nA
Maximum Sensitivity Wavelength	V _R =0V	-	-	550	-	nm
Temp. Coef., Isc	(1)	-	-	+0.2	-	%/ °C
Acceptance Half Angle	(off center-line)	-	-	40	-	deg
Fall Time	V _R =10V, RL=1KΩ(2)	-	-	1.5	-	μS
Rise Time	V _R =10V, RL=1KΩ(2)	-	-	1.0	-	μS

NOTE:

1. Ee = Light Source @2854 °K 2. Ee = Light Source $@\lambda = 560 \text{ nm}$





Spectral Response



Directional Sensitive Characteristics



Mechanical Specifications

Units are in inches [mm]







General Care and Handling Instructions

Photodiodes:

Handling and Storage

- Handle Photodiodes gently to prevent damage.
- Avoid exposing Photodiodes to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

 Gently clean the glass (borosilicate or quartz window) using a 50/50 mixture of Methanol and isopropyl alcohol and a soft, optical-grade pad.

Special Considerations for Plastic or Epoxy Encapsulated Photodiodes

- Protect from intense light sources such as direct sunlight.
 Avoid exposure to harsh chemicals like THINNERS, ACETONE,
- and TRICHLOROETHYLENE.Cleaning with a 50/50 mixture of Methanol and isopropyl
- alcohol (IPA) is recommended. Cleaning in an ultrasonic bath is generally not recommended.

CdS Photocells:

Handling and Storage

- Handle CdS Photocells gently to prevent damage.
- Avoid exposing CdS Photocells to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

- Gently clean the glass or plastic covering using a 50/50
- mixture of Methanol and isopropyl alcohol and a soft, opticalgrade pad.

Special Considerations

 DO NOT use Vapor Phase Soldering or Reflow Soldering for CdS components.

Optocouplers and LEDs:

Handling and Storage

- Handle Optocouplers and LEDs gently to prevent damage.
 Avoid exposing the devices to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

 For plastic molded devices, cleaning with a 50/50 mixture of Methanol and isopropyl alcohol is recommended. Cleaning in an ultrasonic bath is generally not recommended.

Special Considerations

Avoid exposing plastic molded devices or epoxy glob top devices to harsh chemicals like THINNERS, ACETONE, and TRICHLOROETHYLENE.

Legal Disclaimer

Information in this data sheet is believed to be correct and reliable. However, no responsibility is assumed for possible inaccuracies or omission. Specifications are subject to change without notice.



Most of our standard catalog products are RoHS Compliant. Please contact us for details.

Electrostatic Discharge (ESD) Sensitivity:

All devices are considered ESD-sensitive. They are shipped in ESD protective packaging. When unpacking and using these products, anti-ESD precautions should be observed.

Lead Trimming and Bending:

Standard lead trimming after soldering is an acceptable practice; however, do not attempt to bend or modify the leads incorrectly, as it can damage the glass feed-through or the plastic encapsulant.

Soldering Instructions:

- Use a soldering iron with a tip temperature of 300°C max.
- Consult with your preferred solder manufacturer to determine a solder alloy and flux combination, as well as the reflow profile appropriate for your application.

General Precautions for all Devices

1. Moisture Prevention:

Ensure devices are stored in a dry environment to prevent moisture ingress, which can cause damage during soldering. Refer to J-STD-20 for guidance on proper baking procedures to prevent moisture related damage.

2. Lead Splaying:

If required, carefully splay the leads of the devices according to the specific application needs. Be cautious when splaying leads, as improper techniques may damage the device. Consult technical support or device datasheets for guidance on lead splaying.

3. Mechanical Stress:

Handle devices with care throughout the installation process to prevent damage.

4. Circuit Protection and Layout:

Optimize the circuit design and layout to ensure proper functioning and prevent damage to the devices. Include appropriate protection measures like ESD protection diodes, current-limiting resistors, and voltage regulation.

5. After-Sale Support:

For troubleshooting and device-specific inquiries, please consult with our technical support team. They can offer valuable guidance and suggestions on handling, operation, and application-related questions. To reach them, please contact the Advanced Photonix Applications group at Techsupport@advancedphotonix.com.

